

Final Product Change Notification

202404006F01: Introduction of Plasma Dicing Capacity Extension for Plasma Diced UCODE 9

Note: This notice is NXP Company Proprietary.

Issue Date: Apr 11, 2024 Effective Date: Jul 10, 2024

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Management summary

NXP is extending its plasma dicing capacity for plasma diced UCODE 9 products. The commercial type names or 12NCs (ordering codes), and TIDs will not change.

Change Category

[]Wafer Fab Process	[]Assembly Process	[]Product Marking	[]Test Process	[]Design
[]Wafer Fab Materials	[]Assembly Materials	[]Mechanical Specification	[]Test Equipment	[]Errata
[]Wafer Fab Location	[X]Assembly Location	[]Packing/Shipping/Labeling	[]Test Location	[]Electrica spec./Test coverage
[]Firmware	[]Other			

Notification Overview

Description

For the increase of production capacity we extend our plasma dicing location.

• Next to our current plasma dicing site AMKOR (Taiwan), our plasma dicing subcontractor TFME (China) will be enabled.

To be noted:

- There will be no change in type names or 12NCs (ordering code)
- · TIDs will be not changed

Reason

NXP strives to provide larger flexibility in the production fulfilment. Being able to process UCODE 9 plasma diced wafer products at more than one

source will increase capacity and supply stability.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment Jul 15, 2024

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing data sheet

Disposition of Old Products

N/A

Additional information

Self qualification:view online

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by May 11, 2024.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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12NC Orderable Part Number **Product Type Product Description** Product Status Customer Specific Indicator **Product Line** 935430457035 SL3S1206FUD2/HAPZ SL3S1206FUD2/HAP UCODE RFS No BLT1 935430459035 SL3S1216FUD2/HAPAZ SL3S1216FUD2/HAP UCODE RFS No BLT1